

ABSTRACT OF THE DISCLOSURE

5 A mother substrate cutting method for cutting a
plurality of unit substrates out of a mother substrate,
comprises the steps of: (a) forming scribe lines on the mother
substrate by scribe forming means; and (b) breaking the mother
substrate along the scribe lines, wherein the step (a)
includes a step of forming a first scribe line for cutting
a first unit substrate out of the mother substrate and a
10 second scribe line for cutting a second unit substrate out
of the mother substrate by moving the scribe forming means
with respect to the mother substrate without a pressure to
the mother substrate by the scribe forming means being
interrupted.

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